CLAIMS

1. A process for producing an electronic component, comprising: forming a via hole in a base material having a conductor layer on at least one surface thereof by performing laser irradiation from the other surface side of the base material; forming a conductor part in the via hole through deposition of plating in the via hole using the conductor layer as an electrode; and causing an electroless plating to be deposited in the via hole such that an electroless plating layer in close contact with an inner wall surface of the via hole extends in the thickness direction of the conductor part.

2. A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a conductor layer formed on one surface thereof, the process comprising: forming a via hole in the base material having the conductor layer by performing laser irradiation at least from the other surface side of the base material; forming an electroless plating layer in close contact with an inner wall surface of the via hole after deposition of a plating until the core material exposed on the inner wall surface of

the via hole is covered by using the conductor layer as an electrode; and depositing a plating again by using the conductor layer as an electrode to cover the electroless plating layer to thereby form a conductor part in the via hole.

3. A process for producing an electronic component according to Claim 2, wherein the core material is caused to protrude from the inner wall surface of the via hole through laser irradiation to thereby form an anchor structure with respect to the conductor part.

4. A process for producing an electronic component which effects conduction processing between front and back surfaces of a base material equipped with a core material and having a conductor layer formed on one surface thereof, the process comprising: forming a via hole in the base material having the conductor layer by performing laser irradiation at least from the other surface side of the base material; causing the core material to protrude from an inner wall surface of the via hole; and depositing a plating by using the conductor layer as an electrode so as to form an anchor structure together with the core material protruding from the inner wall surface of the via hole to form a

conductor part in the via hole.

5. A process for producing an electronic component according to any one of claims 2 through 4, wherein the core material is formed of glass cloth.

6. An electronic component comprising:

a base material having a conductor layer on at least one surface thereof;

a via hole formed through laser irradiation from the other surface side of the base material;

an electroless plating layer which is in close contact with an inner wall surface of the via hole; and

a conductor part which covers the electroless plating layer and which is formed in the via hole.

7. An electronic component comprising:

a base material equipped with a core material and having a conductor layer on at least one surface thereof;

a via hole formed through laser irradiation from the other surface side of the base material;

a first plating layer formed by using the conductor layer as an electrode so as to cover the core material, which is exposed on an inner wall surface of the via hole;

an electroless plating layer which is formed on the upper side of the first plating layer and which is in close contact with the inner wall surface of the via hole; and

a second plating layer formed by using the conductor layer as an electrode so as to cover the electroless plating layer,

wherein a conductor part is formed in the via hole by the first plating layer, the electroless plating layer, and the second plating layer.

8. An electronic component according to Claim 7, wherein a protrusion is formed on the inner wall surface of the via hole, the protrusion and the conductor part forming an anchor structure.

9. An electronic component according to Claim 8, wherein the protrusion is formed by the core material protruding from the inner wall surface of the via hole.

10. An electronic component according to claim 9, wherein the core material is formed of glass cloth.

11. An electronic component comprising:

a base material having a conductor layer on at least one surface thereof;

a via hole formed through laser irradiation from the other surface side of the base material;

a protrusion protruding from an inner wall surface of the via hole; and

a conductor part which forms an anchor structure together with the protrusion formed in the via hole to be thereby prevented from being detached from the protrusion.

12. An electronic component according to Claim 11, wherein the protrusion is formed by a core material, which is included in the basic material, protruding from the inner wall surface of the via hole.

13. An electronic component according to claim 12, wherein the core material is formed of glass cloth.